

Surface Mount Schottky Barrier Rectifier
Reverse Voltage - 20 to 200V
Forward Current - 3.0A

FEATURES

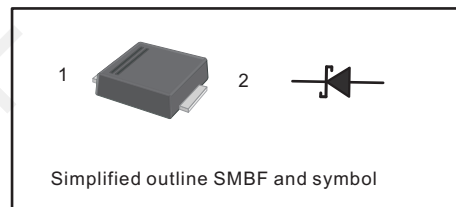
- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SMBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 57mg / 0.002oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS32BF	SS34BF	SS36BF	SS38BF	SS310BF	SS312BF	SS315BF	SS320BF	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	3.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	80				70				A
Max Instantaneous Forward Voltage at 2 A	V _F	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current T _a = 25°C at Rated DC Reverse Voltage T _a = 100°C T _a = 125°C	I _R	0.5 5 /				0.3 / 5				mA
Typical Thermal Resistance ¹⁾	R _{θJA}	50								°C/W
Operating Junction Temperature Range	T _j	-55 ~ +125								°C
Storage Temperature Range	T _{stg}	-55 ~ +150								°C

1) P.C.B. mounted with 0.5 X 0.5" (12.7 X 12.7 mm) copper pad areas.

1) Measured at 1MHz and applied reverse voltage of 4 V D.C.

2) P.C.B. mounted with 0.5 X 0.5" (12.7 X 12.7 mm) copper pad areas.



Fig.1 Forward Current Derating Curve

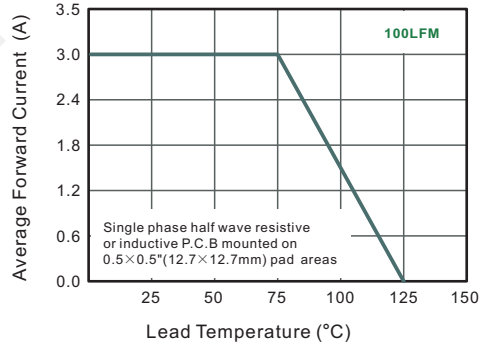


Fig.2 Typical Reverse Characteristics

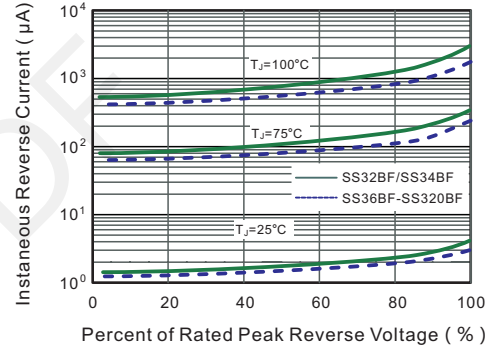


Fig.3 Typical Forward Characteristic

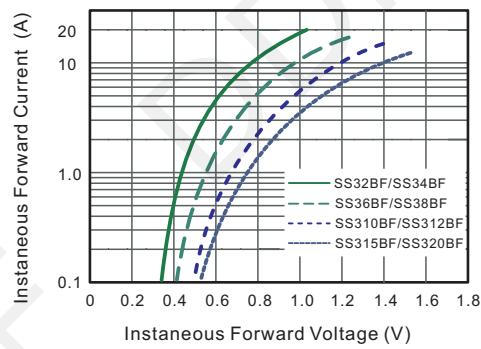


Fig.4 Maximum Non-Repetitive Peak Forward Surge Current

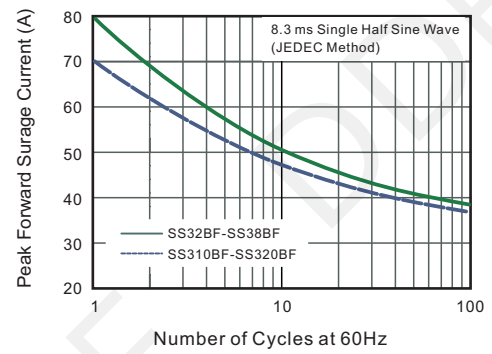
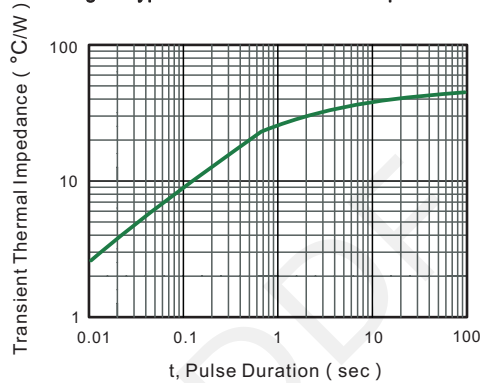


Fig.5- Typical Transient Thermal Impedance

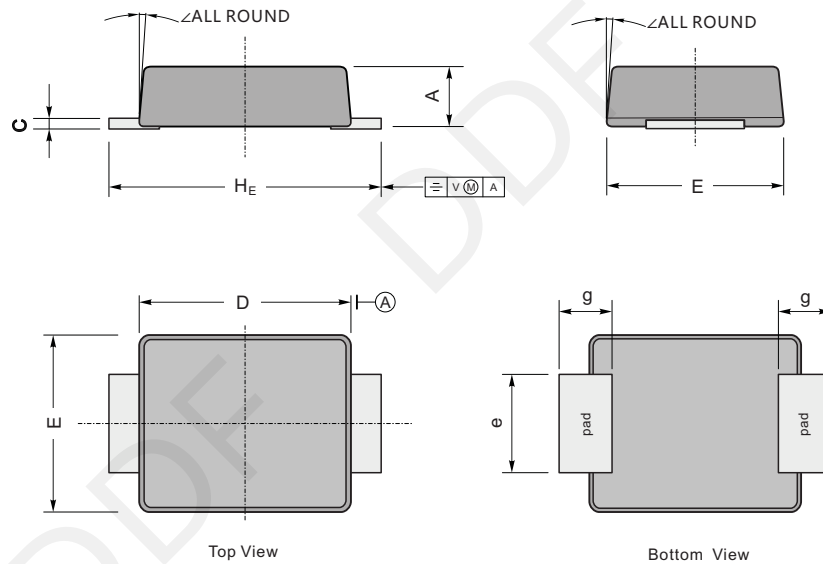




PACKAGE OUTLINE

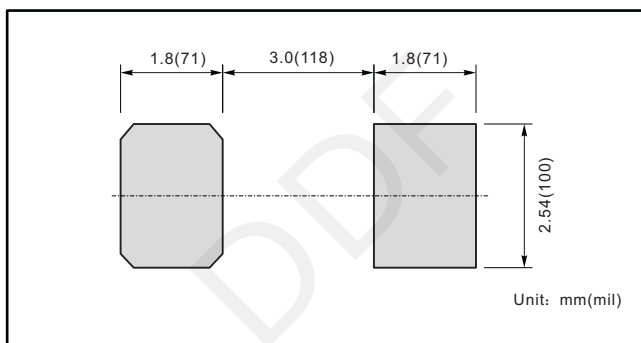
Plastic surface mounted package; 2 leads

SMBF



UNIT		A	C	D	E	H _E	e	g	∠
mm	max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	9°
	min	1.1	0.18	4.2	3.5	5.1	1.9		
mil	max	51	10	173	146	216	86	40	
	min	43	7	165	138	200	75		

The recommended mounting pad size



Marking

Type number	Marking code
SS32BF	S32B
SS34BF	S34B
SS36BF	S36B
SS38BF	S38B
SS310BF	S310B
SS312BF	S312B
SS515BF	S315B
SS520BF	S320B